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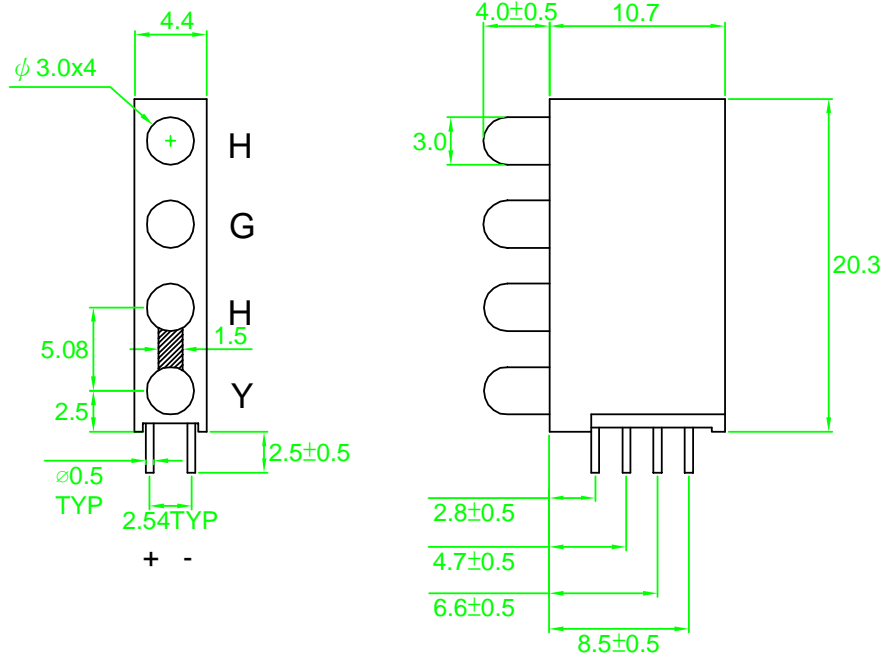
**LED ARRAY**

Lead-Free Parts

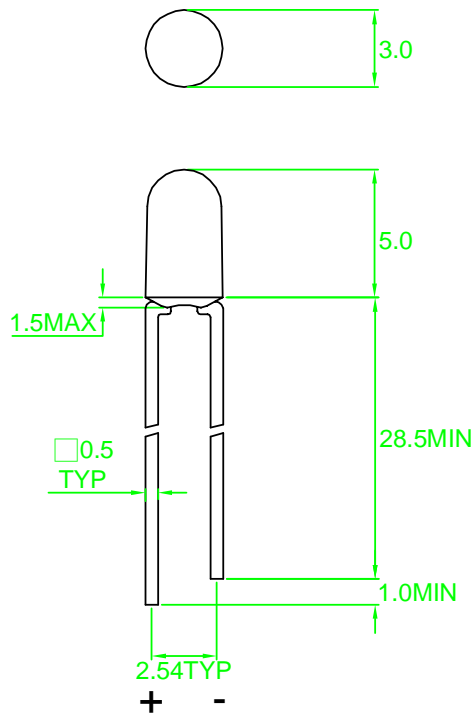
**LA79B-1/HGHY-PF****DATA SHEET**DOC. NO : QW0905-LA79B-1/HGHY-PFREV. : ADATE : 03 - Aug. - 2009



### Package Dimensions



LH2340-1/F181-PF  
 LG2340-1/F181-PF  
 LY2340-1/F181-PF



Note : 1.All dimension are in millimeter tolerance is  $\pm 0.25$ mm unless otherwise noted.  
 2.Specifications are subject to change without notice.

**Absolute Maximum Ratings at Ta=25 °C**

Parameter	Symbol	Ratings			UNIT
		H	G	Y	
Forward Current	IF	15	30	20	mA
Peak Forward Current Duty 1/10@10KHz	IFP	60	120	80	mA
Power Dissipation	PD	40	100	60	mW
Reverse Current @5V	Ir	10			μA
Operating Temperature	Topr	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +100			°C

**Typical Electrical & Optical Characteristics (Ta=25 °C)**

PART NO	MATERIAL	COLOR		Peak wave length λ Pnm	Spectral halfwidth Δ λ nm	Forward voltage @ 20mA(V)		Luminous intensity @ 10mA(mcd)		Viewing angle 2θ 1/2 (deg)
		Emitted	Lens			Min.	Max.	Min.	Typ.	
LA79B-1/HGHY-PF	GaP	Red	Red Diffused	697	90	1.7	2.6	1.8	3.0	80
	GaP	Green	Green Diffused	565	30	1.7	2.6	8.0	20	80
	GaAsP/GaP	Yellow	Yellow Diffused	585	35	1.7	2.6	8.0	20	80

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.  
2. The luminous intensity data did not including ±15% testing tolerance.



### Typical Electro-Optical Characteristics Curve

H CHIP

Fig.1 Forward current vs. Forward Voltage

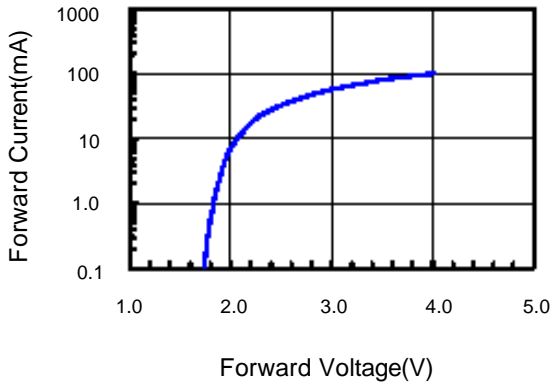


Fig.2 Relative Intensity vs. Forward Current

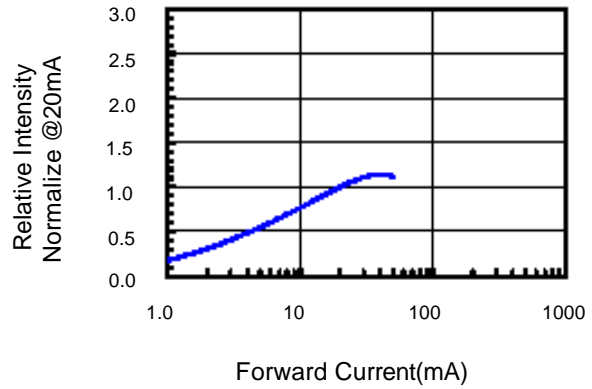


Fig.3 Forward Voltage vs. Temperature

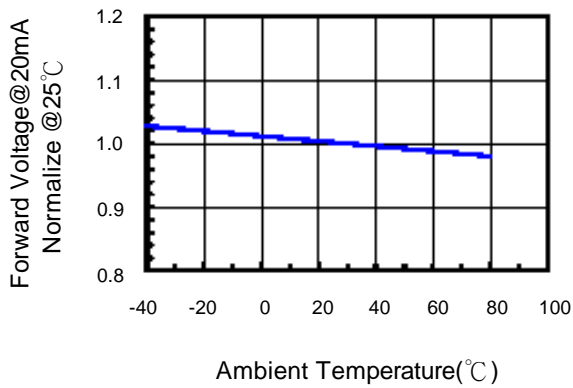


Fig.4 Relative Intensity vs. Temperature

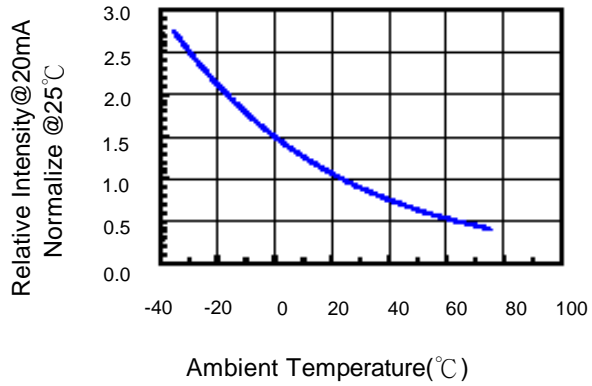
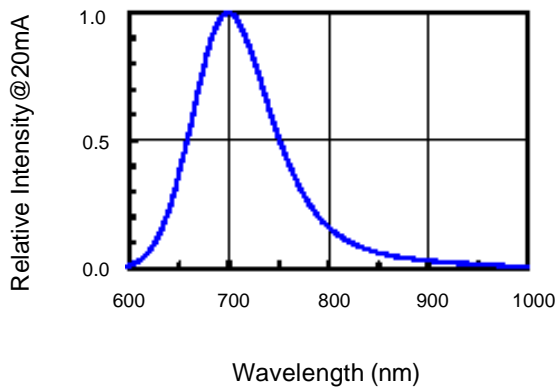


Fig.5 Relative Intensity vs. Wavelength





### Typical Electro-Optical Characteristics Curve

G CHIP

Fig.1 Forward current vs. Forward Voltage

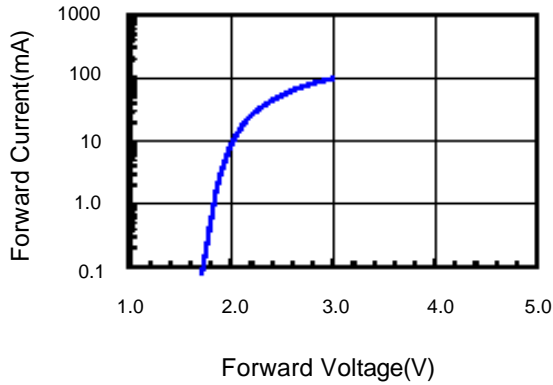


Fig.2 Relative Intensity vs. Forward Current

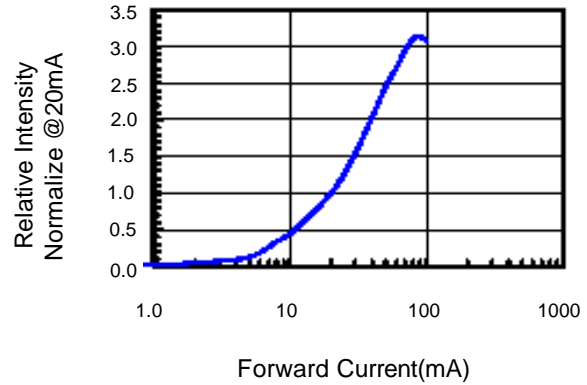


Fig.3 Forward Voltage vs. Temperature

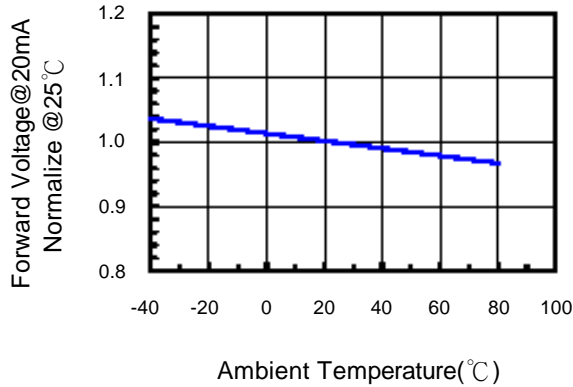


Fig.4 Relative Intensity vs. Temperature

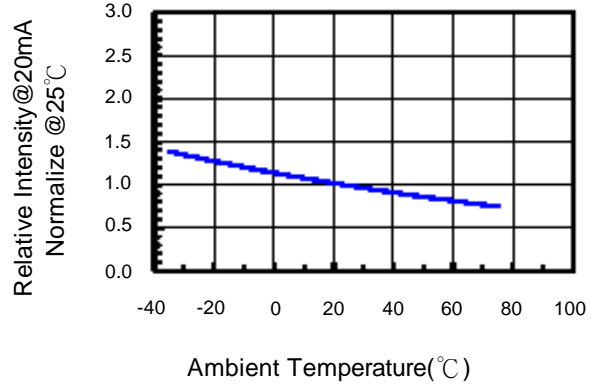
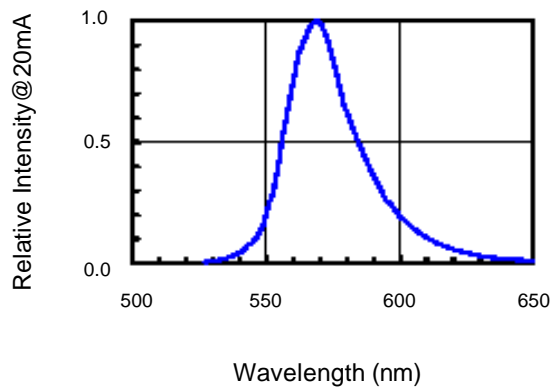


Fig.5 Relative Intensity vs. Wavelength





### Typical Electro-Optical Characteristics Curve

Y CHIP

Fig.1 Forward current vs. Forward Voltage

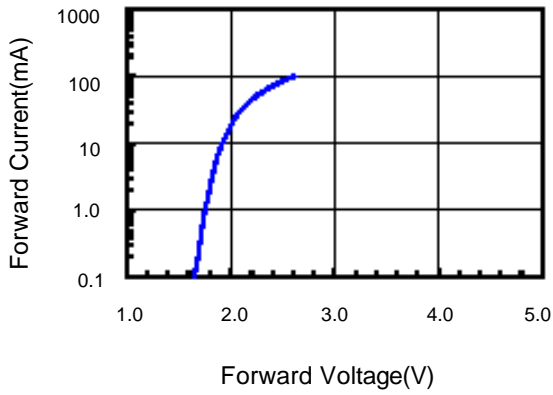


Fig.2 Relative Intensity vs. Forward Current

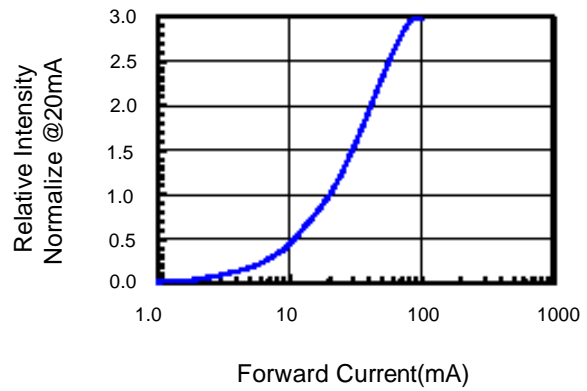


Fig.3 Forward Voltage vs. Temperature

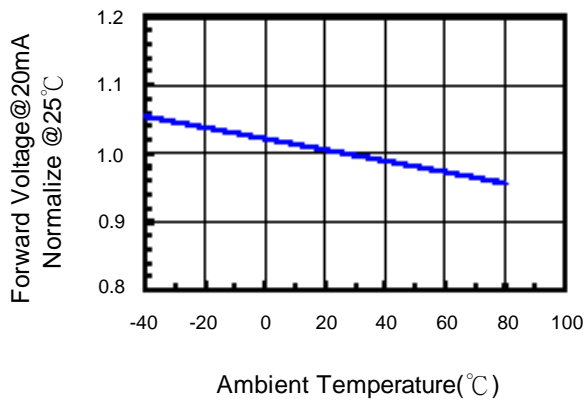


Fig.4 Relative Intensity vs. Temperature

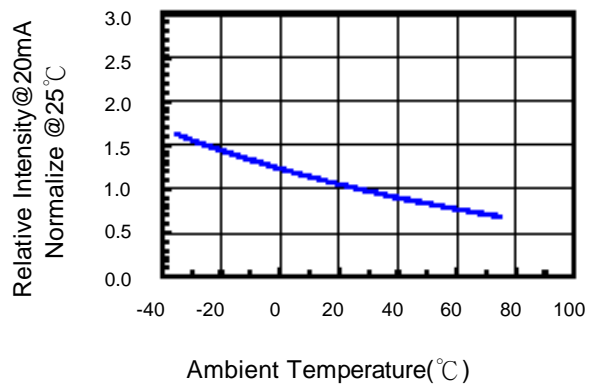
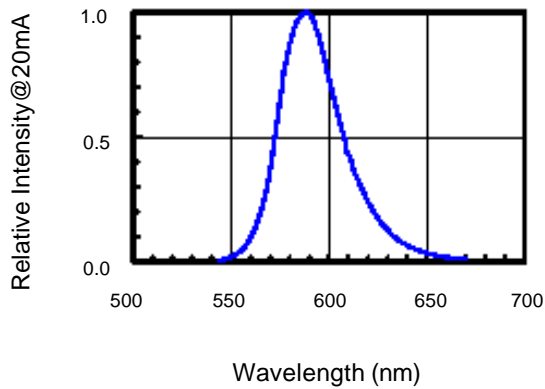


Fig.5 Relative Intensity vs. Wavelength





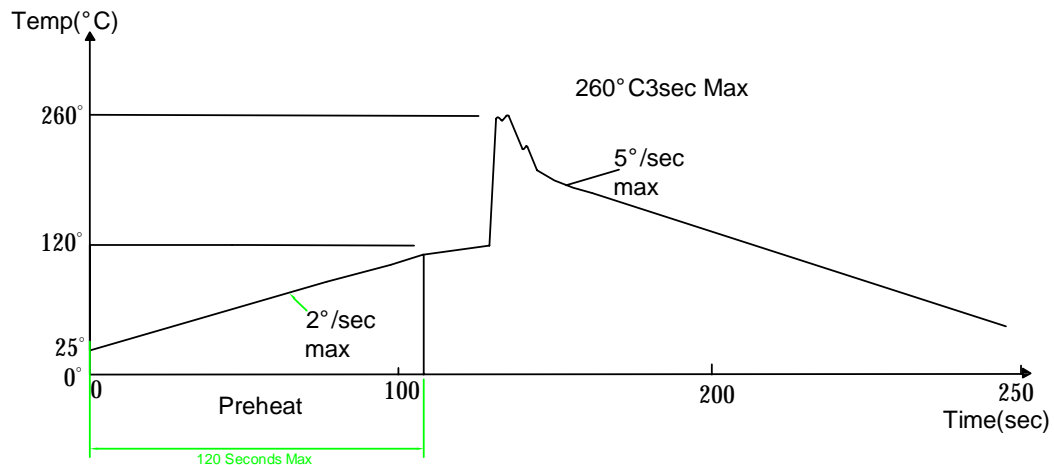
### Soldering Condition(Pb-Free)

#### 1.Iron:

Soldering Iron:30W Max  
Temperature 350°C Max  
Soldering Time:3 Seconds Max(One time only)  
Distance:2mm Min(From solder joint to case)

#### 2.Wave Soldering Profile

Dip Soldering  
Preheat: 120°C Max  
Preheat time: 120seconds Max  
Ramp-up  
2°C/sec(max)  
Ramp-Down:-5°C/sec(max)  
Solder Bath:260°C Max  
Dipping Time:3 seconds Max  
Distance:2mm Min(From solder joint to case)



Note: 1.Wave solder should not be made more than one time.  
2.You can just only select one of the soldering conditions as above.

**Reliability Test:**

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105 °C ±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 °C ±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 °C ±5°C 2.RH=90%~95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 °C ±5°C & -40°C ±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 °C ±5°C 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 °C ±5°C 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2